

Abstract

An LED die (3) is arranged with an adhesive (4) on an LED PCB (6). The LED PCB (6) has on the side opposite to the LED die (3) rear side contacts (7).
5 Through this a self-contained LED lamp is formed, which e.g. can be applied by means of SMT to a board (9) or introduced into a lamp socket. In accordance with the invention, the rear side contacts (7) cover at least the half area, preferably the entire area apart from necessary exceptions, of the LED PCB (6). Through this, the heat can be discharged with slight thermal
10 resistance. Preferably a cooling body (11) is arranged on the rear side of the board (9). In this case it is expedient if the board (9) has through-contacts for increasing the thermal conductivity.

NY_Main 580610_1